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PATENT NUMBER and ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10066849	FILING DATE 02/04/2002	CLASS 430	SUBCLASS 311	GAU 1756 4762	EXAMINER Duda Ruggles
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****CONTINUING DATA VERIFIED:**

**** FOREIGN APPLICATIONS VERIFIED:**
REPUBLIC OF KOREA 2001-38772 06/30/2001

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PG-FUB	DO NOT PUBLISH <input type="checkbox"/>	RESCIND <input type="checkbox"/>	ATTORNEY DOCKET NO 29926/38060
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no	
Verified and Acknowledged Examiners's initials		TITLE : Method for manufacturing multi-level interconnections with dual damascene process	

U.S. DEPT. OF COMM. / PAT. & TM. / PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Assistant Examiner	Total Claims Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drawg.	Fig. Drawg. Print Fig.
		Primary Examiner	Application Examiner
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
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